



μGalv R&D is a turn-key electroplating system for various metals (Au, Ni, Cu) as well as additional rinsing cells or quick dump rinsers are available.

The μGalv Pro system is the ideal platform for electroplating applications from intensive R&D to pilot production.

Body	Material: standard PP white, optional PPs white, PVDF (with yellow card), elements CNC machined and welded
Operating Elements, electrical, regulation units, pneumatics	All process operating elements are integrated into the front panel, all electrical and pneumatically components are integrated in an independent compartment in the back side service area, DI-H ₂ O and N ₂ -Spray gun integrated in the workdeck.
Plating Module	Overflow process consisting of a process cell and reserve tank with overflow/filtration circuit. Electroforming of pure metals like Ni, Cu, Au, Ag, ... Electro less plating of Ni, Au, SnPb Process cell configuration as rack plater Depending on electrolyte, pH control (Acid and/or base) or cooling integrated Pulse plating with minimum pulse time of 0.10 msec, reverse pulse optional
Wafer holder	PEEK, with stainless steel 1.4404 contact ring and gold plated wafer contacts, various edge exclusions available, min 3.5 mm edge exclusion
Cleaning Module	Standard Overflow-Rinsler, optional Mega sonic Cell washing module, optional QDR-module, optional SRD (Spin-Rinse-Dryer)
Process options	Process Cell with multiple process slots (including separate rectifiers) Basket handling in the case of electro less plating Pulse & reverse pulse rectifier with minimum pulse time of 0.1 msec
Standard components	Valves: membrane valves, ball valves, different diameter Pump: centrifugal pump made of PP, optional PVDF Filter housing: PP 10", optional PVDF PP plumbing, optional PVDF or PFA tube 1/2", 3/4", 1" with PFA flaretek fittings Remark: customized solutions available if requested
Other options	Integration of pre or post process cells possible Laminar-flow-units Vacuum twizer Quick connector fluid drain

